

ABSTRACT

WAFER PROCESSING METHOD

Disclosed herein is a wafer processing method including a transfer step of transferring a wafer to a holding surface of a chuck table by using a transfer unit having a suction pad, next holding the front side of the wafer through a protective tape on the holding surface of the chuck table under suction, and next removing the suction pad from the back side of the wafer and a modified layer forming step of applying a laser beam to the back side of the wafer held on the holding surface of the chuck table, thereby forming a modified layer inside the wafer along each division line. The transfer step includes a mounting step of mounting the wafer held by the suction pad to the holding surface of the chuck table, a sandwiching step of removing a suction force applied to the suction pad and then sandwiching the wafer between the suction pad and the holding surface of the chuck table, and a suction holding step of applying a suction force to the holding surface of the chuck table to thereby hold the front side of the wafer through the protective tape on the holding surface of the chuck table under suction, and next removing the suction pad from the back side of the wafer.

(Figure 7C)